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Part Number:

0736420000

Status:

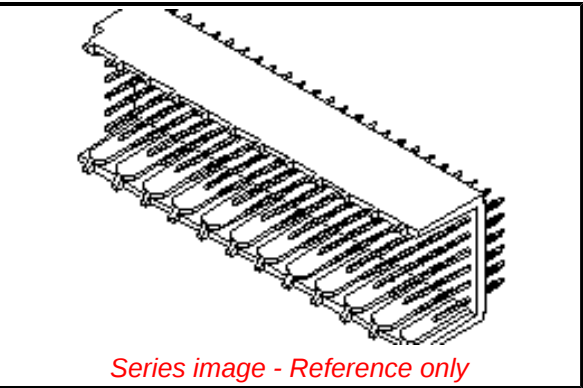
Active

Overview:

HDM® Backplane Connector System

Description:

HDM® Board-to-Board Backplane Header, Vertical, Press-Fit, Open End, 72 Circuits



Series image - Reference only

Documents:	
3D Model	Product Specification TS-73670-990-001 (PDF)
Drawing (PDF)	Packaging Specification PK-70873-0818 (PDF)
Product Specification PS-73670-9999 (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73642
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	HDM® Backplane Connector System
Product Name	HDM®
UPC	800754345057
Physical	
Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	3.371/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	1.60mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.051µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

EU ELV	
Not Relevant	
EU RoHS	China RoHS
Compliant	
REACH SVHC	
Not Contained Per	
-ED/01/2017 (12	
January 2017)	
Halogen-Free	
Status	
Low-Halogen	
Need more information on product	
environmental compliance?	
Email productcompliance@molex.com	
Please visit the Contact Us section for any	
non-product compliance questions.	
China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

73642 Series

Mates With

73632 HDM+® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999, TS-73670-990-001
Sales Drawing	SDA-73642-****

Note: HDM, HDM+, VHDM, VHDM-HSD and GbX are trademarks or registered trademarks of Amphenol TCS.

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